

Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Please cancel claims 1 to 14 without prejudice or disclaimer.

Please add new claims 15 to 31 as follows:

Claims 1-14 (canceled).

Claim 15 (new): A laminate, comprising:

a conductive metal layer for an electronic circuit; and

a porous insulating film,

wherein the conductive metal layer is laminated on one or both sides of the porous insulating film either directly or via a heat resistant adhesive layer, and

wherein the porous insulating film comprises a highly heat resistant resin film having a fine porous structure with

a mean pore size of 0.01 to 5 μm in at least the center of the film,

a void volume of 15 to 80%, and

a heat shrinkage factor of no greater than $\pm 1\%$ as measured at 105° C for 8 hours.

Claim 16 (new): The laminate according to claim 15, wherein an inorganic, organic or metal substrate is laminated on one side of the porous insulating film and the conductive metal layer is laminated on the other side.

Claim 17 (new): The laminate according to claim 16, wherein the inorganic or metal substrate and the conductive metal layer are each laminated to the porous insulating film via a heat resistant adhesive layer.

Claim 18 (new): The laminate according to claim 15, wherein the mean pore size is 0.01 to 2 μm .

Claim 19 (new): The laminate according to claim 15, wherein the mean pore size is 0.01 to 1 μm .

Claim 20 (new): The laminate according to claim 15, wherein the heat resistant resin film contains fine continuous channels with a mean pore size of 0.01 to 5 μm in the center and both surfaces of the film that reach to both surfaces of the film in a nonlinear fashion.

Claim 21 (new): The laminate according to claim 15, wherein the void volume is 30 to 80%.

Claim 22 (new): The laminate according to claim 15, wherein the porous insulating film has a thickness of 5 to 150 μm .

Claim 23 (new): The laminate according to claim 15, wherein the fine porous structure consists of fine continuous pores.

Claim 24 (new): The laminate according to claim 15, wherein the porous insulating film is fabricated by a film casting method.

Claim 25 (new): The laminate according to claim 15, wherein the porous insulating film has a permittivity of no greater than 2.5.

Claim 26 (new): The laminate according to claim 15, wherein the highly heat resistant resin film is a polyimide film.

Claim 27 (new): The laminate according to claim 15, wherein the porous structure has fine continuous pores reaching to both surfaces.

Claim 28 (new): The laminate according to claim 15, wherein the porous structure has

a void volume of 30-80%,
a pore size of no greater than 10 μm ,
a film thickness of 5 to 100 μm ,
a gas permeability of from 30 sec/100 cc to 2000 sec/100 cc, and
a heat resistance temperature of at least 200° C.

Claim 29 (new): The laminate according to claim 15, wherein the porous structure has a dense layer on both surfaces of the film.

Claim 30 (new): The laminate according to claim 15, wherein the porous insulating film comprises a polyimide, comprising

a tetracarboxylic acid component that includes a biphenyltetracarboxylic acid,
and
an aromatic diamine component that includes paraphenylenediamine or
diaminodiphenylether.

Claim 31 (new): The laminate according to claim 15, wherein the porous insulating film has a dielectric constant of no greater than 2.5 as measured at a frequency of 1000 Hz or 10 MHz.